

Title (en)
COMPONENT FOR MODIFYING THE IMPEDANCE OF A COPLANAR WAVEGUIDE AND METHOD FOR PRODUCING SUCH A COMPONENT

Title (de)
BAUTEIL ZUR IMPEDANZÄNDERUNG BEI EINEM KOPLANAREN WELLENLEITER SOWIE VERFAHREN ZUR HERSTELLUNG EINES BAUELEMENTS

Title (fr)
COMPOSANT POUR LA MODIFICATION DE L'IMPEDANCE DANS UN GUIDE D'ONDES COPLANAIRE, ET PROCEDE DE PRODUCTION D'UN TEL COMPOSANT

Publication
EP 1665315 B1 20111012 (DE)

Application
EP 04762505 A 20040724

Priority
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• DE 10342938 A 20030917

Abstract (en)
[origin: US2007229198A1] A component is provided for an impedance change in a coplanar waveguide which includes two grounding conductors and a signal line lying between the grounding conductors, as well as a conducting connecting element, which has a covering surface for the two grounding conductors and the signal line, and is electrically insulated, so that in each case a capacitor is formed. The connecting element and the lines are situated and arranged so that the respective capacitor between the grounding conductors and the connecting element has an invariable capacitance, but the capacitor between the connecting element and the signal line has a variable capacitance. A structure is also provided in which in an exactly opposite way, the respective capacitor between the grounding conductors and the connecting element has a variable capacitance, but the capacitor between the connecting element and the signal line has an invariable capacitance. Furthermore, a method for producing such a component is also provided.

IPC 8 full level
H01H 59/00 (2006.01)

CPC (source: EP US)
H01H 59/0009 (2013.01 - EP US); **Y10T 29/49105** (2015.01 - EP US)

Citation (examination)
• DE 10037385 A1 20020214 - BOSCH GMBH ROBERT [DE]
• YOSHIDA Y. ET AL: "A novel grounded coplanar waveguide with cavity structure", PROCEEDINGS OF THE IEEE 16TH. ANNUAL INTERNATIONAL CONFERENCE ON MICRO ELECTRO MECHANICAL SYSTEMS. MEMS 2003. KYOTO, JAPAN, AN. 19 - 23, 2003, 19 January 2003 (2003-01-19), KYOTO, JAPAN, pages 140 - 143, XP010636929

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DOCDB simple family (publication)
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